# **BOURNS®**

- 1 A Continuous On-State Current
- 15 A Surge-Current
- Glass Passivated Wafer
- 400 V to 600 V Off-State Voltage
- I<sub>GT</sub> 50 μA min, 200 μA max
- di/dt 100A/μs
- Package Options

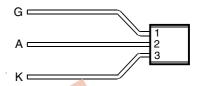
PACKAGE	PACKING	PART # SUFFIX		
LP	Bulk	(None)		
LP with fomed leads	Tape and Reel	R		

### LP PACKAGE (TOP VIEW)



MDC1AA

#### LP PACKAGE WITH FORMED LEADS (TOP VIEW)



MDC1AB

## absolute maximum ratings over operating junction temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT	
Repetitive peak off-state voltage (see Note 1)	TICP107D	V	400	V	
nepetitive peak off-state voltage (see Note 1)	TICP107M	$V_{DRM}$	600	· '	
Repetitive peak reverse voltage	TICP107D	V	400	V	
nepetitive peak reverse voltage	TICP107M	$V_{RRM}$	600	'	
Continuous on-state current at (or below) 25°C ambient temperature (see Note 2)			1	Α	
Surge on-state current at (or below) 25°C ambient temperature (see Note 3)			15	Α	
Critical rate of rise of on-state current at 110°C (see Note 4)			100	A/µs	
Peak positive gate current (pulse width ≤ 300 μs)			0.2	Α	
Junction temperature range		$T_J$	-40 to +110	°C	
Storage temperature range			-40 to +125	°C	
Lead temperature 3.2 mm from case for 10 seconds			230	°C	

- NOTES: 1. These values apply when the gate-cathode resistance  $R_{GK}$  = 1  $k\Omega$ .
  - 2. These values apply for continuous dc operation with resistive load.
  - 3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
  - 4. Rate of rise of on-state current after triggering with  $I_G = 10$ mA,  $di_G/dt = 1$ A/ $\mu$ s.



### electrical characteristics at 25°C ambient temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = rated V <sub>DRM</sub>	R <sub>GK</sub> = 1 kΩ				20	μΑ
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>R</sub> = rated V <sub>RRM</sub>	$I_G = 0$				200	μΑ
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 12 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs	50		200	μΑ
V <sub>GT</sub>	Gate trigger voltage	V <sub>AA</sub> = 12 V	$R_L = 100 \Omega$	t <sub>p(g)</sub> ≥ 20 μs	0.4		1	V
I <sub>H</sub>	Holding current	V <sub>AA</sub> = 12 V		Initiating I <sub>T</sub> = 10 mA			2	mA
V <sub>T</sub>	On-state voltage	I <sub>T</sub> = 2 A	(see Note 5)				1.4	V

NOTE 5: This parameter must be measured using pulse techniques, t<sub>p</sub> = 1 ms, duty cycle ≤ 2 %. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

